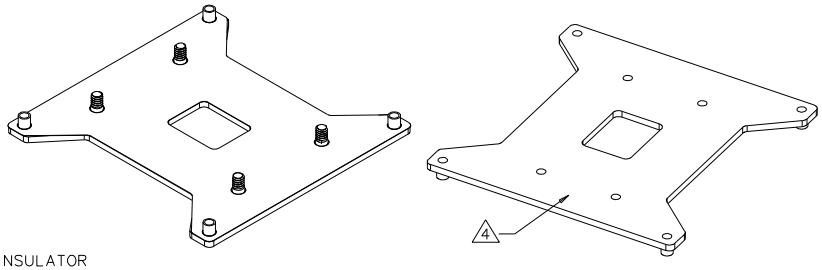
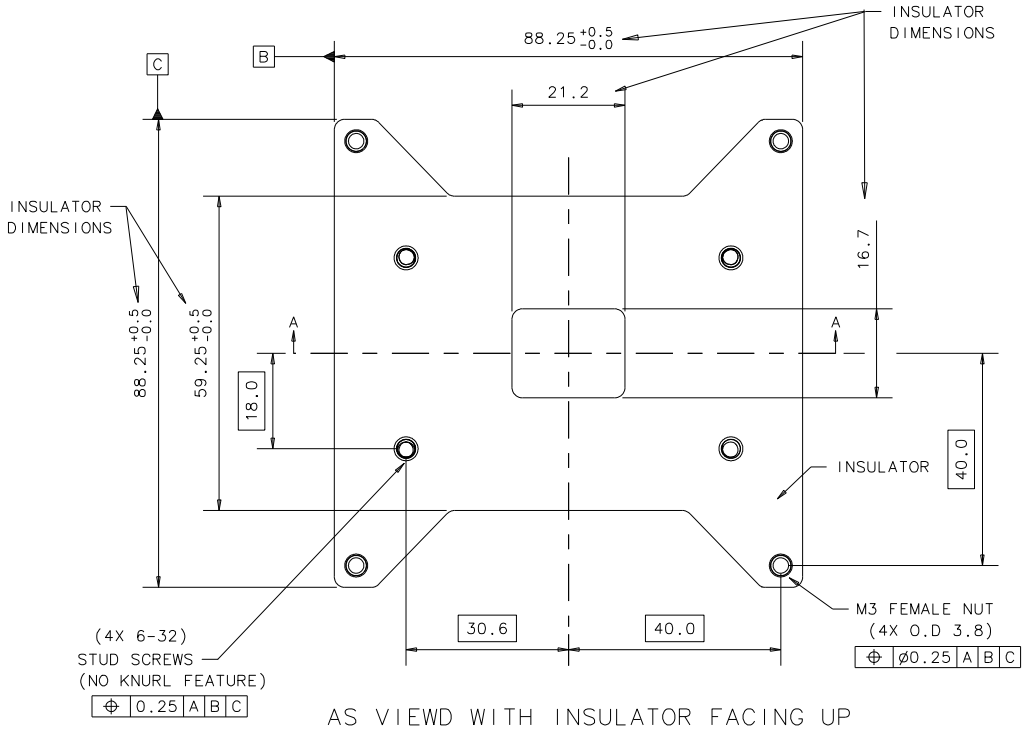
IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

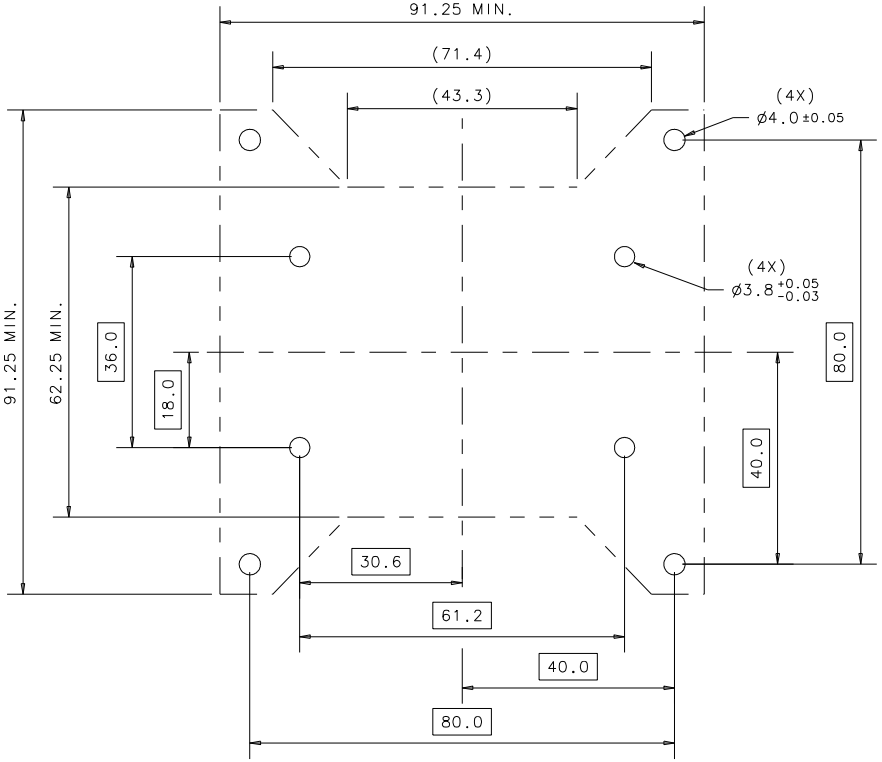
REV.	ECN. NO.	APPD.
A	BC077030675	N.LIN
B	BC097035380	N.LIN
C	BC100087839	N.LIN
D	BC100093890	N.LIN

NOTES:
1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MATERIAL : SERVER BACK PLATE — CARBON STEEL / THICKNESS 2.2MM
   PLATING ON BACK PLATE — 100u" MIN. Zn PLATING OVERALL
   STUD SCREWS — STEEL;
   FEMALE NUTS — STEEL
   INSULATOR — INSULATIVE MATERIAL / THICKNESS 0.178MM
4. "FOXCONN" "DATECODE" "13XXBPYR" ARE LOCATED APPROXMIATELY.
5. HARMFUL MATERIAL CONTROL PLEASE FOLLOW DOC. N.O. "EPI12".
6. PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.

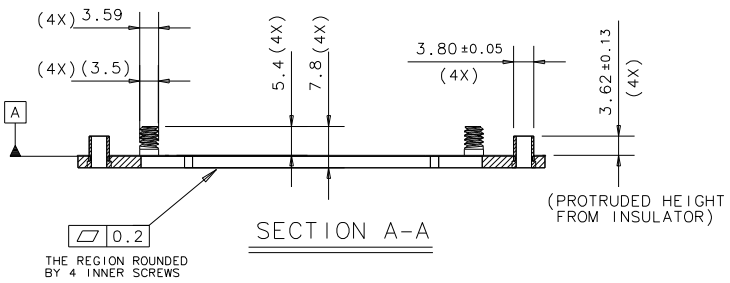




AS VIEWD WITH INSULATOR FACING UP



RECOMMENDED PCB KEEPOUT ZONE



SECTION A-A

X.±	X.°±	UNITS mm	NAME(INTENDED USE) LGA13XX SV BP
.X± 0.30	.X°±	MAT'L	
.XX± 0.25	.XX°±		PART NO.(INTENDED USE) PT44P12-4105
.XXX±	.XXX°±	FINISH	
		Q'TY	APPD: Nick Lin
			CHKD: Bill He
			DR: Barrry 08/26'10

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FOXCONN
HON HAI PRECISION IND. CO.,LTD.
TAIPEI, TAIWAN, R.O.C.

TITLE: CUSTOMER DRAWING FOR LGA13XX SERVER BACK PLATE (ZINC-PLATED BACK PLATE)

DWG NO.: 351-0000-1066

SCALE	SHEET	REV.
1/1	1/1	D